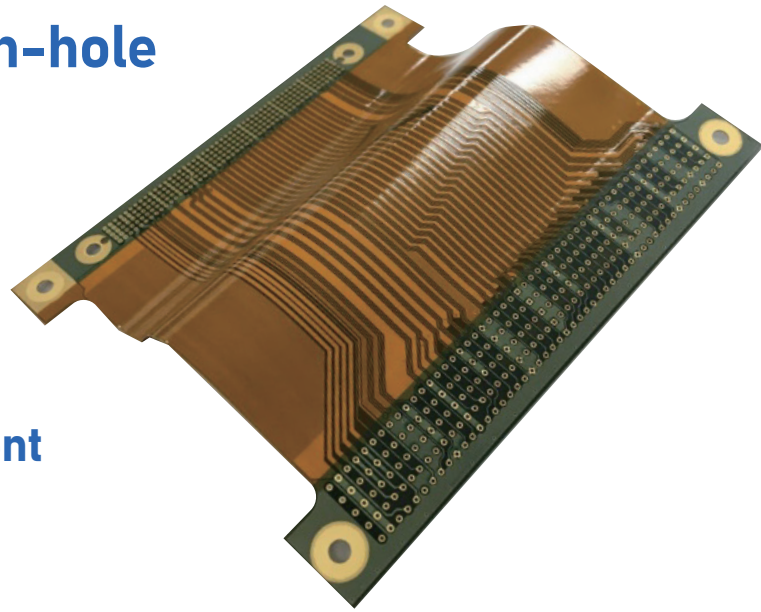


High-Density High-Multilayer FPC

Provides a plate thickness of 0.98 mm by use of a 12-layer through-hole structure!

- Flight data recorder
- Liquid crystal display
- Information processing equipment



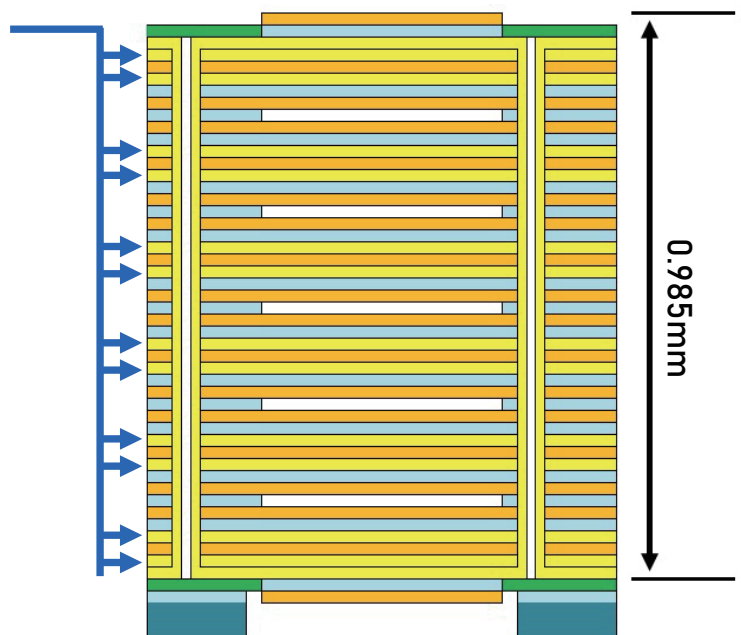
Features

- A harness portion can be used with the harness bent.
- Most suitable when you want to perform a high-density wiring of 200 pins or more in the limited space.

Structure example

Conductor layer consisting of 12 layers

Minimum pattern width	200 μ m
Minimum hole diameter	ϕ 0.5mm
Minimum land diameter	Φ 0.8mm
FPC thickness	0.985mm
FPC overall thickness	2.625mm
Outer layer base materials	25 μ m
Outer layer conductor thickness (Including TH plating)	20+9 μ m
Inner layer base materials	12.5 μ m
Inner layer conductor thickness	18 μ m



YAMASHITA MATERIALS